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Design Guide for RF/ Microwave Circuit Boards

IPC-2252

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A standard developed by IPC

Supersedes IPC-D-316
June 1995

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Developed by the High Speed/High Frequency Design Task Group
(D-21b) of the High Speed/High Frequency Committee (D-20) of IPC

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Acknowledgment

Any Standard involving a complex technology draws material from a vast number of sources. While the principal members of the High Speed/High Frequency Design Task Group (D-21b) of the High Speed/High Frequency Committee (D-20) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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